



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/632,553

Filed: August 2, 2003

Title: **Semiconductor multi-package module having
package stacked over die-down flip chip ball
grid array package and having a wire bond
interconnect between stacked packages**

Examiner: Dao H. Nguyen

Group Art Unit: 2818

Date: October 26, 2005.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on October 26, 2005.

Signed

Bill Kennedy

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed April 26, 2005, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the claims are reflected in the **Listing of Claims** which begins on page 3 of this paper.

Remarks begin on page 8 of this paper.